

Appl. No. 10/055,499
Amdt. dated June 01, 2006
Reply to Office action of March 01, 2006

Amendments to the Claims:

Claims 1-280 (canceled)

5 281. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

joining a die and a substrate, wherein said die has a top surface at a horizontal level; and

10 after said joining said die and said substrate, depositing a gold bump over said horizontal level, ~~wherein said bump comprises gold.~~

282. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

joining multiple dies and a substrate;

15 depositing an insulating layer over ~~a die~~ said multiple dies and said substrate, wherein said insulating layer comprises a porous structure; and

separating said substrate into multiple portions.

20 283. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

joining multiple dies ~~a die~~ and a substrate, wherein one of ~~said multiple dies~~ ~~die~~ has a top surface at a horizontal level; and

after said joining said multiple dies ~~die~~ and said substrate, depositing a passive device over said horizontal level; and

25 separating said substrate into multiple portions.

284. (currently amended) A method for fabricating a circuitry ~~an electronic component~~,

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comprising:

joining multiple dies and a substrate, wherein one of said multiple dies has a top surface at a horizontal level;

- 5 providing a die having a top surface at a horizontal level; and
waveguide over said horizontal level; and
separating said substrate into multiple portions.

285. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

- 10 providing a die having a top surface at a horizontal level; and
depositing a micro electronic mechanical sensor (MEMS) over said horizontal level.

286. (currently amended) A method for fabricating a circuitry ~~an electronic component~~, comprising:

- 15 depositing an insulating layer over a circuitry element;
curing said insulating layer;
grinding said insulating layer; and
depositing a metal layer over said insulating layer.

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